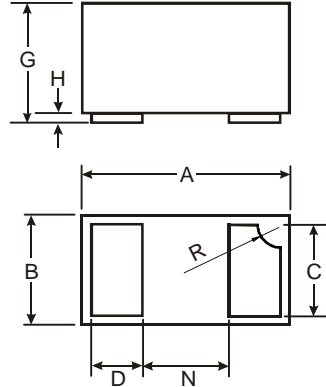


**Features**

- Fast Switching Speed
- Ultra-Small Leadless Surface Mount Package
- For General Purpose Switching Applications
- Lead Free By Design/RoHS Compliant (Note 1)
- "Green" Device (Note 2)
- Qualified to AEC-Q101 Standards for High Reliability

**Mechanical Data**

- Case: DFN1006-2
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020C
- Terminal Connections: Cathode Dot
- Terminals: Finish - NiPdAu over Copper leadframe. Solderable per MIL-STD-202, Method 208
- Marking Information: See Page 2
- Ordering Information: See Page 2
- Weight: 0.0009 grams



DFN1006-2			
Dim	Min	Max	Typ
A	0.95	1.075	1.00
B	0.55	0.675	0.60
C	0.45	0.55	0.50
D	0.20	0.30	0.25
G	0.47	0.53	0.50
H	0	0.05	0.03
N	—	—	0.40
R	0.05	0.15	0.10

All Dimensions in mm

**Maximum Ratings** @T<sub>A</sub> = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Non-Repetitive Peak Reverse Voltage	V <sub>RM</sub>	100	V
Peak Repetitive Reverse Voltage	V <sub>RRM</sub>	75	V
Working Peak Reverse Voltage	V <sub>RWM</sub>		
DC Blocking Voltage	V <sub>R</sub>		
RMS Reverse Voltage	V <sub>R(RMS)</sub>	53	V
Forward Continuous Current	I <sub>FM</sub>	300	mA
Average Rectified Output Current	I <sub>O</sub>	200	mA
Non-Repetitive Peak Forward Surge Current	I <sub>FSM</sub>	2.0	A
		1.0	

@ t = 1.0μs  
@ t = 1.0s

**Thermal Characteristics**

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 3)	P <sub>d</sub>	250	mW
Thermal Resistance Junction to Ambient Air (Note 3)	R <sub>θJA</sub>	500	°C/W
Operating and Storage Temperature Range	T <sub>j</sub> , T <sub>STG</sub>	-65 to +150	°C

**Electrical Characteristics** @T<sub>A</sub> = 25°C unless otherwise specified

Characteristic	Symbol	Min	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 4)	V <sub>(BR)R</sub>	75	—	V	I <sub>R</sub> = 100μA
Forward Voltage	V <sub>F</sub>	—	0.715	V	I <sub>F</sub> = 1.0mA
			0.855		I <sub>F</sub> = 10mA
			1.0		I <sub>F</sub> = 50mA
			1.25		I <sub>F</sub> = 150mA
Leakage Current (Note 4)	I <sub>R</sub>	—	1.0	μA	V <sub>R</sub> = 75V
			50		V <sub>R</sub> = 75V, T <sub>j</sub> = 150°C
			30		V <sub>R</sub> = 25V, T <sub>j</sub> = 150°C
			25		V <sub>R</sub> = 20V
Total Capacitance	C <sub>T</sub>	—	2.0	pF	V <sub>R</sub> = 0, f = 1.0MHz
Reverse Recovery Time	t <sub>rr</sub>	—	4.0	ns	I <sub>F</sub> = I <sub>R</sub> = 10mA, I <sub>rr</sub> = 0.1 x I <sub>R</sub> , R <sub>L</sub> = 100Ω

- Notes:
1. No purposefully added lead.
  2. Diodes Inc.'s "Green" policy can be found on our website at [http://www.diodes.com/products/lead\\_free/index.php](http://www.diodes.com/products/lead_free/index.php).
  3. Part mounted on FR-4 PC board with recommended pad layout, which can be found on our website at <http://www.diodes.com/datasheets/ap02001.pdf>.
  4. Short duration pulse test used to minimize self-heating effect.

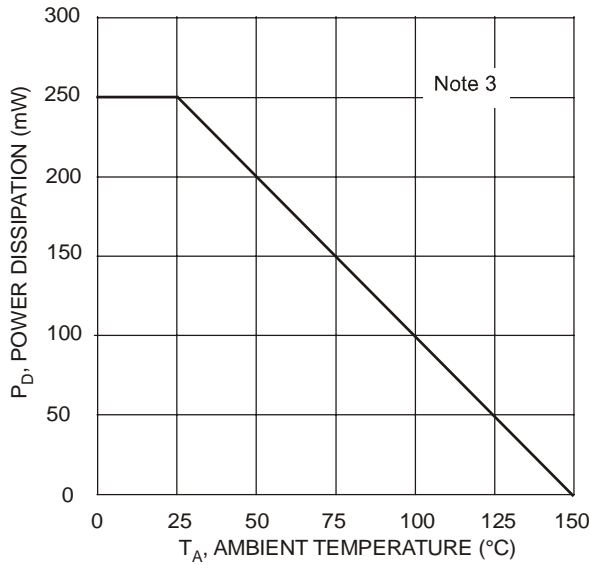


Fig. 1 Power Derating Curve

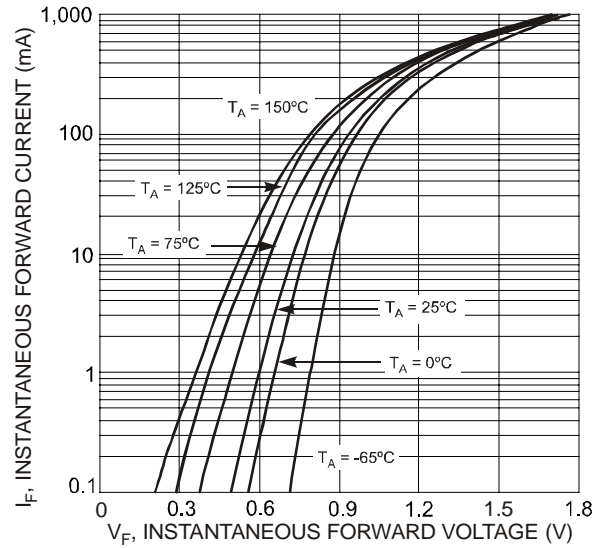


Fig. 2 Typical Forward Characteristics

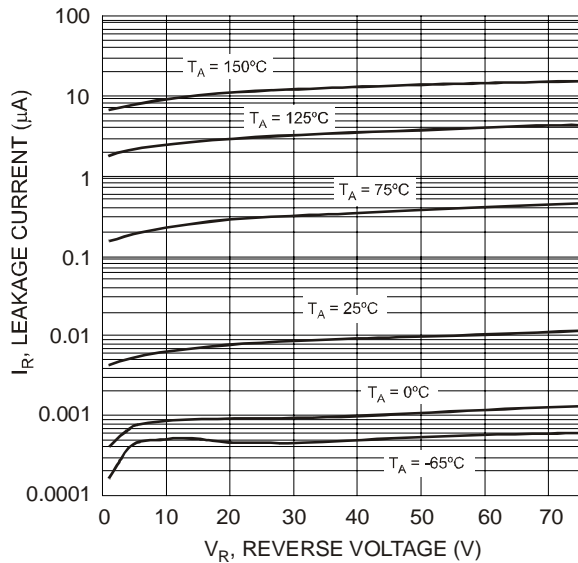


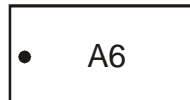
Fig. 3 Typical Reverse Characteristics

## Ordering Information (Note 5)

Device	Packaging	Shipping
BAS16LP-7	DFN1006-2	3000/Tape & Reel

Notes: 5. For packaging details, go to our website at <http://www.diodes.com/datasheets/ap02007.pdf>.

## Marking Information



A6 = Product Type Marking Code, Dot Denotes Cathode Side

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